

providing a dielectric core;

helically winding a conductive wiring circumferentially around the dielectric core; and

cutting, normal to an axis of the dielectric core, through the conductive wiring and

through the dielectric core, at two locations along the axis, leaving a conductive button between

the two location as having a first end and a second end, wherein the conductive wiring terminates

in at least two end contacts at the first end, and wherein the conductive wiring terminates in at

least two end contacts at the second end.

The present invention reduces the probability of failure of the electrical coupling between two substrates of an electrical structure. Additionally, the present invention facilitates repairing or upgrading of the electrical structure.

Brief Description of the Drawings

FIG. 1 depicts a top view of a substrate with an array of conductive pads on a surface of the substrate, in accordance with the related art.

FIG. 2 depicts a cross-sectional view of an electrical structure comprising two substrates electrically and mechanically joined at corresponding conductive pads by a conductive button, in accordance with the related art.

FIG. 3 depicts a cross-sectional view of two substrates electrically and mechanically coupled at corresponding conductive pads by conductive buttons, in accordance with embodiments of the present invention.

FIG. 4 depicts a perspective view of a dielectric core, in accordance with embodiments of

the present invention.

FIG. 5 is depicts conductive wiring helically wound around the dielectric core of FIG. 4.

FIG. 6 depicts the helical wiring of FIG. 5 as braided.

FIG. 7 depicts the helical wiring of FIG. 5 as served.

5 FIG. 8 depicts an outer dielectric jacket extruded onto the helically wired dielectric core of FIG. 5, thus forming a conductive rod.

FIG. 9 depicts a cross-sectional view of the dielectric jacket extrusion process of FIG. 8.

FIG. 10 depicts the conductive rod of FIG 8 after being inserted into a dielectric place holder.

10 FIG. 11 depicts FIG. 10 after the conductive rod and similar conductive rods have been axially cut, leaving conductive buttons in the dielectric place holder.

FIG. 12 depicts a cross-sectional view of end contacts of a conductive button, said end contacts created by mechanical cutting of a conductive rod from which the conductive button was formed, in accordance with embodiments of the present invention.

15 FIG. 13 depicts FIG. 3 with conductive buttons being soldered to one of the two substrates, in accordance with embodiments of the present invention.

FIG. 14 depicts FIG. 13 after conductive buttons have been soldered to the other of the two substrates, in accordance with embodiments of the present invention.

Detailed Description of the Invention

20 FIG. 3 depicts a cross-sectional view of substrates 32 and 34 electrically and

mechanically joined at corresponding conductive pads 33 and 35, respectively, by conductive buttons 38, in accordance with embodiments of the present invention. The word, “conductive,” (and variants thereof such as “conductively”) herein means “electrically conductive” unless otherwise noted. The conductive pads 33 and the conductive pads 35 each constitute a two-dimensional array of electrically conductive pads (e.g., gold or gold-plated pads). The substrate 34 may include, *inter alia*, a printed wiring board (PWB). The substrate 32 may include, *inter alia*, an electronic module such as a chip carrier with one or more attached semiconductor chips.

The conductive button 38 electrically couples the substrate 32 at the pad 33 to the substrate 34 at the pad 35. Each conductive button 38 comprises a dielectric core 40, a conductive wiring 42 helically wound around the dielectric core 40, and an outer dielectric jacket 44 around the conductive wiring 42. The conductive wiring 42 terminates in the end contacts 47 at an end 41 of the button 38, where the end contacts 47 mechanically and electrically contact the pad 35. The conductive wiring 42 also terminates in the end contacts 48 at an end 43 of the button 38, where the end contacts 48 mechanically and electrically contact the pad 33. As a result, the substrate 32 is conductively coupled to the substrate 34 by the following conductive path: pad 33, end contacts 48, conductive wiring 42, end contacts 47, and pad 35.

The aforementioned mechanically and electrically contacting of the end contacts 47 and 48 to the pads 35 and 33, respectively, is accomplished by application of a compressive force 46 (e.g., clamping) on the electrical structure 30. The compressive force 46 is transmitted to the pads 33 and 35 where the transmitted force on the pads 33 and 35 is directed toward the button 38. A dielectric place holder 36 holds the buttons 38 in place. The dielectric place holder 36 is